**TOSHIBA** 2SK2614

**TENTATIVE** 

TOSHIBA FIELD EFFECT TRANSISTOR SILICON N CHANNEL MOS TYPE (L²-π-MOS V)

# 2 S K 2 6 1 4

HIGH SPEED, HIGH CURRENT SWITCHING APPLICATIONS CHOPPER REGULATOR, DC-DC CONVERTER AND MOTOR DRIVE **APPLICATIONS** 

4V Gate Drive

Low Drain-Source ON Resistance  $: R_{DS(ON)} = 0.032\Omega \text{ (Typ.)}$ 

High Forward Transfer Admittance :  $|Y_{fs}| = 8S$  (Typ.)

:  $I_{DSS} = 100 \mu A$  (Max.) Low Leakage Current

 $(V_{DS}=50V)$ 

 $: V_{th} = 0.8 \sim 2.0 V$ Enhancement-Mode

 $(V_{DS} = 10V, I_D = 1mA)$ 

#### MAXIMUM RATINGS (Ta = 25°C)

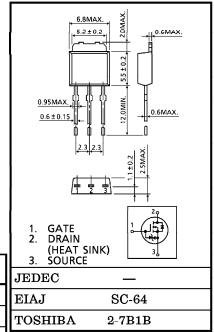
CHARACTERIST	SYMBOL	RATING	UNIT		
Drain-Source Voltage	$v_{ m DSS}$	50	V		
Drain-Gate Voltage (RGS	$V_{ m DGR}$	50	v		
Gate-Source Voltage	$V_{GSS}$	±20	V		
Drain Current	DC	$I_{\mathrm{D}}$	20	A	
Drain Current	Pulse	$I_{\mathrm{DP}}$	50		
Drain Power Dissipation	$P_{\mathbf{D}}$	40	W		
Channel Temperature	${ m T_{ch}}$	150	°C		
Storage Temperature Ran	$\mathrm{T_{stg}}$	-55~150	°C		

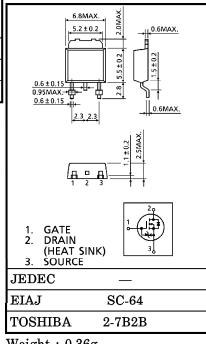
#### THERMAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	MAX.	UNIT
Thermal Resistance, Channel to Case	R <sub>th (ch-c)</sub>	3.125	°C/W
Thermal Resistance, Channel to Ambient	R <sub>th (ch-a)</sub>	125	°C/W

This transistor is an electrostatic sensitive device. Please handle with caution.

#### INDUSTRIAL APPLICATIONS Unit in mm





Weight: 0.36g

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## ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARAC	CTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Gate Leakage	Current	IGSS	$V_{GS} = \pm 16V, V_{DS} = 0V$	_	_	±10	$\mu$ A
Drain Cut-off	Current	$I_{ m DSS}$	$V_{DS}=50V, V_{GS}=0V$			100	$\mu$ A
Drain-Source Voltage	Breakdown	V <sub>(BR)</sub> DSS	$I_D=10$ mA, $V_{GS}=0$ V	50	_	_	V
Gate Thresho	ld Voltage	$V_{ m th}$	$V_{DS}=10V, I_{D}=1mA$	0.8	_	2.0	V
Drain-Source	ON Resistance	R <sub>DS</sub> (ON)	$V_{GS}=4V, I_{D}=5A$ $V_{GS}=10V, I_{D}=10A$		0.055	0.08	Ω
Forward Tran Admittance	sfer	$ Y_{fs} $	$V_{DS} = 10V, I_{D} = 10A$	7	13	_	S
Input Capacit	ance	Ciss		_	900	_	
Reverse Transfer Capacitance Output Capacitance		$C_{rss}$	$V_{DS}$ =10V, $V_{GS}$ =0V, f=1MHz	-	130	_	pF
		Coss		_	370	_	
Switching Time Fall Time	Rise Time	t <sub>r</sub>	V <sub>GS ov</sub> I <sub>D</sub> =10A o V <sub>out</sub>		15	_	
	Turn-on Time	t <sub>on</sub>	V <sub>GS</sub> <sub>0V</sub>	1	25	_	ng
	Fall Time	$t_f$	V <sub>DD</sub> ≒30V		30		ns
	Turn-off Time	toff	$egin{aligned}  ext{VIN}:  ext{t_r},  ext{t_f} < 5  ext{ns}, \  ext{Duty} \leq 1\%,  ext{t_W} = 10 \mu  ext{s} \end{aligned}$	_	100	_	
Total Gate Charge (Gate- Source Plus Gate-Drain)		$\mathbf{Q}_{\mathbf{g}}$		_	25	_	nC
Gate-Source Charge		$\mathbf{Q}_{\mathbf{g}\mathbf{s}}$	$V_{DD} = 40V, V_{GS} = 10V, I_D = 20A$	_	19	_	
Gate-Drain ("Miller") Charge		$\mathbf{Q}_{\mathrm{gd}}$		_	6	_	

## SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	$I_{ m DR}$	_	_	1	20	A
Pulse Drain Reverse Current	$I_{ m DRP}$	_		1	50	Α
Diode Forward Voltage	$v_{ m DSF}$	$I_{DR}$ =20A, $V_{GS}$ =0V	_	_	-1.7	V
Reverse Recovery Time	$t_{rr}$	$I_{ m DR} = 20  m A, \ V_{ m GS} = 0  m V \ dI_{ m DR} / dt = 50  m A / \ \mu s$	_	60	_	ns
Reverse Recovery Charge	$Q_{ m rr}$		_	45	_	$\mu$ C

### MARKING

